

# SEMICON® EUROPA

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semi

## CxO Summit

### Welcome Remarks

L. Altimime  
President  
SEMI Europe, Berlin, Germany



### Abstract

Coming Soon

### Biography

Laith Altimime, as President of SEMI Europe, leads SEMI's activities in Europe and the Middle East and Africa (EMEA). Altimime has P&L responsibility as well as ownership of all Europe region programs and events, including SEMICON Europa. He is responsible for establishing industry standards, advocacy, community development, expositions, and programs. He provides support and services to SEMI members worldwide that have supply chain interests in Europe. He manages and nurtures relationships with SEMI members in the region and globally as well as with local associations and constituents in industry, government, and academia. Altimime has more than 30 years of international experience in the semiconductor industry. Prior to joining SEMI in 2015, He held senior leadership positions at NEC, KLA-Tencor, Infineon, Qimonda and imec. Altimime holds an MSc from Heriot-Watt University, Scotland.

References

## Opening Remarks

A. Manocha  
President and CEO  
SEMI, Milpitas, United States of America



## Abstract

Coming Soon

## Biography

Ajit Manocha is the president and CEO of SEMI. Headquartered in Milpitas, California, SEMI is the global industry association serving the electronics manufacturing and design supply chain. Throughout his career, Manocha has been a champion of industry collaboration as a critical means of advancing technology for societal and economic prosperity.

Manocha was formerly CEO at GLOBALFOUNDRIES. Prior to this he held the role of EVP of worldwide operations at Spansion and earlier served as EVP and chief manufacturing officer at Philips/NXP Semiconductors. He began his career at AT&T Bell Laboratories as a research scientist where he was granted more than a dozen patents related to semiconductor manufacturing processes that served as the foundation for modern microelectronics manufacturing. He has served on the boards of SEMI, SIA and GSA. Today, there is a much broader scope for SEMI to help foster collaboration and fuel growth than we could have ever imagined at its inception in 1970. This scope has to be accomplished without compromising the strong foundation of SEMI – the equipment suppliers and materials makers. Manocha feels SEMI must evolve as the industry's ecosystem rapidly expands to support smarter, connected applications based on artificial intelligence, machine learning and other disruptive technologies.

Manocha is active on global advocacy and workforce development issues and has served on the President's committees for "Advanced Manufacturing Partnerships" and the President's Council of Advisors on Science & Technology (PCAST).

In 2021, VLSIresearch added Manocha to its Semiconductor Industry Hall of Fame for his leadership of SEMI efforts to address geopolitical trade tensions as well as for his initiative in navigating the many challenges of the COVID-19 pandemic impacting SEMI and the microelectronics industry. In 2020, Manocha was inducted into the Silicon Valley Engineering Hall of Fame, and VLSI named him an "All Star of the Semiconductor Industry" for his visionary leadership in 2019 to restructure SEMI to represent the expanded electronics supply chain.

References

## Topic Coming Soon

G. Kalbe  
Acting Director of DG Connect C, Digital  
Excellence and Science Infrastructure  
European Innovation Council, Brussels, Belgium



### Abstract

Coming Soon

### Biography

DG Communications Networks, Content and Technology, European Commission, Acting Director of DG Connect C “Digital Excellence and Science Infrastructure” and Head of Unit of the High Performance Computing and Quantum Technology unit

Dr. Gustav Kalbe studied Applied Physics at the Université Catholique de Louvain, Belgium. In 1991 he studied Applied Optics at the Imperial College of Science in London. In 1995 he completed his studies and earned a PhD in Physics at the Université Catholique de Louvain, Belgium.

He started his professional career as a project manager in photonic networks at the incumbent telecom operator in Belgium. He was R&D manager when he left the company.

In 1998 he joined the Directorate General Information Society & Media of the European Commission where he started working as Project Officer managing research projects of the European Framework Programs for Research. Over the years he had several assignments in quantum technologies, photonics, and cybersecurity.

In 2014 Gustav Kalbe became Head of Unit for Administration & Finance in the European Commission, in Directorate General Communications Networks, Content and Technology.

In 2016 he was appointed Head of Unit of the newly created High Performance Computing and Quantum Technology unit in Directorate General Communications Networks, Content and Technology.

In 2018 he became responsible for the establishment and operation of the European High Performance Computing Joint Undertaking. He occupied the post of Interim Executive Director of the Joint Undertaking until its autonomy by the end of 2020.

In January 2021, he was appointed Deputy to the Director of DG Connect C “Digital Excellence and Science Infrastructure”.

Since May 2022 Gustav is the Acting Director of DG Connect C “Digital Excellence and Science Infrastructure”.

References

## **Chips Joint Undertaking: Working Together to Strengthen European Industries**

J. Kinaret  
Executive Director  
Chips Joint Undertaking (Chips JU),, Brussels,  
Belgium



### **Abstract**

The Chips Joint Undertaking is funded by the European Union (represented by the EC), Participating States, and Private Members (AENEAS, EPoSS, and INSIDE Industry Associations).

The Chips JU is the European tri-partite partnership that will boost the development and adoption of advanced nano-electronic chip-technologies and systems manufactured in Europe, supporting European sovereignty, digitalisation of society, energy transition, and more, respecting the European values and this to the greater good of the European citizen society and environment.

The Chips JU will develop, together with the European nanoelectronics community and the Member States, in the coming years a strong portfolio comprising several pilot lines for advanced nanoelectronics' technologies, a design platform for the design of advanced chips, a broad set of projects that make use of those technologies to innovate all along the value chain in all industrial domains: mobility, energy, health, robotics, and of course chip manufacturing. This portfolio of actions will be supported with a network of competence centres all over Europe that will facilitate the access to those actions for European start-ups, SMEs, universities, and larger companies.

### **Biography**

Jari Kinaret was born in Finland and holds M.Sc. degrees in Theoretical Physics and Electrical Engineering from the University of Oulu in 1986 and 1987, respectively, and a Ph.D. in Physics from the Massachusetts Institute of Technology (MIT) in 1992.

Prof. Kinaret has worked in various roles at research institutes and universities in Copenhagen, Denmark, and Gothenburg, Sweden. From 2013 to 2023, he served as the Director of the Graphene Flagship, a one-billion-euro research project dedicated to exploring the potential of graphene.

In October 2023, Prof. Jari Kinaret assumed the role of Executive Director at Chips Joint Undertaking (Chips JU), a European public-private partnership that supports research, development, innovation, and future manufacturing capacities in the European semiconductor ecosystem.

References

## Topic Coming Soon

L. Van den hove  
President & CEO  
imec, Leuven, Germany



### Abstract

Coming Soon

### Biography

Luc Van den hove is President and CEO of imec since July 1, 2009. Before he was executive vice president and chief operating officer. He joined imec in 1984, starting his research career in the field of silicide and interconnect technologies. In 1988, he became manager of imec's micro-patterning group (lithography, dry etching); in 1996, department director of unit process step R&D; and in 1998, vice president of the silicon process and device technology division. In January 2007, he was appointed as imec's EVP & COO. Luc Van den hove received his PhD in electrical engineering from the KU Leuven, Belgium. In 2023, he was honored with the Robert N. Noyce medal for his leadership in creating a worldwide research ecosystem in nanoelectronics technology with applications ranging from high-performance computing to health. He has authored or co-authored more than 200 publications and conference contributions.

References

## Topic Coming Soon

K. Beckmann  
Member of the Executive Board and CEO  
Electronics  
Merck KGaA, Darmstadt, Germany



## Abstract

Coming Soon

## Biography

Kai Beckmann, born on September 13, 1965 in Hanau, Germany, joined the Executive Board of Merck in April 2011. He is responsible for the Electronics business sector (formerly Performance Materials), which he has been leading as CEO since September 2017. In October 2018, Kai Beckmann took also over the responsibility for the Darmstadt site and Inhouse Consulting. In addition, he acts as Country Speaker Germany with responsibility for co-determination matters.

Prior to his current role, Kai Beckmann was Chief Administration Officer of Merck with responsibility for Group Human Resources, Group Business Technology, Group Procurement, Inhouse Consulting, Site Operations and Merck Business Services as well as Environment, Health, Safety, Security, Quality. In 2007, he became the first CIO of Merck, with responsibility for Corporate Information Services. From 2004 to 2007, he served as Managing Director of the Merck companies in Singapore and Malaysia, and prior to that he held senior executive responsibility for the Information Management and Consulting unit from 1999 to 2004. He began his career at Merck in 1989 as an IT system consultant.

Kai Beckmann studied computer science at the Technical University of Darmstadt from 1984 to 1989. In 1998, he earned a doctorate in Economics while working.

References

## Topic Coming Soon

O. Wyrsh  
President and Chief Executive Officer  
INFICON HOLDING AG, Zurich, Switzerland



## Abstract

Coming Soon

## Biography

Oliver Wyrsh became President and Chief Executive Officer of INFICON HOLDING AG on January 1, 2023. He joined INFICON in 2018 as President and General Manager of the US business.

Mr. Wyrsh is a Swiss citizen and holds a Master's degree in Computer Science and Business Administration from the Swiss Federal Institute of Technology in Zurich (ETH). He began his career in 2004 as a management consultant at Accenture and Booz & Co before becoming Head of Engineering at a pharmaceutical-focused software startup. He then spent seven years at Mettler Toledo in Germany and the US in various roles - most recently as Head of the Machine Vision Inspection Strategic Business Unit.

References

## Deep Tech Collaboration for Power-Efficient Semiconductors

S. Haferl  
Chief Executive Officer  
Comet Group, Zurich, Switzerland



### Abstract

As artificial intelligence (AI) accelerates the demand for high-performance computing, the need for powerful but energy-efficient microchips becomes ever more important. Today's power-hungry chips present significant challenges across industries, from mobile devices to data centers. While advanced packaging techniques offer promising avenues for enhancing microchip power efficiency, their inherent complexity necessitates robust partnerships within the deep tech ecosystem.

Collaboration from chip design to packaging is vital for developing increasingly complex semiconductor structures and devices. Working together to create advanced inspection methods that effectively verify the integrity of sophisticated packaging solutions, minimizing defects that could lead to disfunctions and higher power consumption, is equally demanding and important. In this context, future-proof X-ray inspection solutions play a pivotal role in maintaining both performance and energy efficiency.

By fostering innovation and co-creation, the semiconductor industry can usher in the next generation of energy-efficient devices, effectively addressing the pressing challenges posed by power-hungry microchips

### Biography

Born 1972, Swiss and Norwegian citizen; Master's degree in mechanical and process engineering from the Swiss Federal Institute of Technology (ETH), Zurich, PhD with work on thermodynamics and fluid dynamics. Stephan Haferl has been working for the Comet Group successfully in various management positions since 2007. His strong track record includes proven performance in business development, innovation, technology, and product management, among other areas.

Before, he held the positions of General Manager at Bartec-Meta Physics SA and Chief Operating Officer at Bartec Bacab SA.

References

## Topic Coming Soon

P. Barnabé  
CEO  
Soitec, Paris, France



### Abstract

Coming Soon

### Biography

Pierre Barnabé was nominated as Soitec CEO in January 2022 and joined the company four months later. He was previously Executive Vice-President in charge of Big Data & Cybersecurity at technology group Atos (2015-2021), where he also led the Public Sector & Defense division and manufacturing operations before serving as interim Group CEO in 2021. Prior to its acquisition by Atos in 2014, Pierre Barnabé was Deputy CEO of Bull. He then served as Bull's Chairman & CEO from 2015 to 2021, spearheading the company's evolution into a global leader in cybersecurity services and supercomputing. From 2011 to 2013, he was Managing Director of the Enterprise branch of SFR, the French telecoms operator, where he launched cloud computing and very high-speed broadband activities. That followed a 13-year stint during which he held various positions at Alcatel and Alcatel-Lucent, first in sales and later as Chairman & Managing Director of Alcatel-Lucent France (formerly Alcatel CIT) and Group Deputy Managing Director for Human Resources and Transformation. A graduate of the NEOMA Business School and Ecole Centrale in Paris, Pierre Barnabé began his career in 1994 in Silicon Valley, developing corporate venture capital and capital risk activities for Thales Group. He then moved to Thales headquarters in Paris, where he was in charge of strategy and acquisitions for the Communication and Command division. A member of the board of the multinational market firm Ipsos, he also served as Chairman of the Board of ENSIMAG Grenoble, the prestigious Grande École specializing in computer science, applied mathematics and telecommunications (2016-2022) and on the board of France's National Institute for Research in Digital Science and Technology (INRIA) from 2021 to 2022. Pierre Barnabé is a Knight of the French National Order of Merit.

References

## **Green Growth: Guiding the Future of the Global Semiconductor Industry**

F. Godomel  
Executive Vice President – Power Systems &  
Services  
Schneider Electric, Paris, France



### **Abstract**

Did you know that the use of semiconductors has doubled every three years? If this trend continues, the semiconductor industry could account for nearly 20% of global energy consumption by 2030! While ramping up semiconductor production is essential to support our technological progress, prioritizing decarbonization and sustainability is crucial. Join us in this session to learn more about how to create an efficient and sustainable fab of the future.

### **Biography**

Coming Soon

References

## Beyond Simulation: Bridging the Real & Digital World

K. Westrich  
Global VP of Electronics, Semiconductors &  
Simulation Digital Industries  
Siemens AG, Munich, Germany



### Abstract

In the semiconductor industry, innovation starts by challenging the status quo. With companies tackling talent gaps and the challenge of building efficient, sustainable multi-billion-dollar fabs, Siemens sees digital twin technology as the game-changer. This powerful technology can supercharge virtual training to upskill teams faster and boost fab productivity and planning like never before. In this keynote, Siemens reveals how the digital twin is fueling breakthroughs and redefining what's possible, helping us all do more with less.

### Biography

Katharina leads Siemens' global activities for Electronics & Semiconductor and Simulation, where she heads a team focused on unlocking the potential of resilient, smart, and sustainable semiconductor manufacturing across the entire value chain. As an elected member of the Governing Council of the Semiconductor Climate Consortium (SCC), Katharina reinforces her commitment to sustainability and her role in driving positive change within the semiconductor ecosystem. Her dynamic and accomplished leadership places her at the forefront of digitalization and sustainability solutions – transforming the everyday through innovative technologies.

Before her current role, Katharina served as the Head of Siemens Research & Pre-Development department. With a team of approximately 500 talented individuals, she championed sustainable practices and contributed to the development of next-generation Siemens products for Integrated Circuits & Electronics, Power Electronics, Sustainable Energy & Infrastructure, Additive Manufacturing, and User Experience. Prior to that, she held several strategic positions within Siemens and gained valuable experience in consulting and mergers & acquisitions for Siemens.

Katharina holds a Master of Science degree from the Catholic University Eichstaett-Ingolstadt.

### Short Version:

Katharina heads Siemens' global activities for Electronics & Semiconductor and Simulation, leading a team dedicated to unlocking the potential of resilient, smart, and sustainable semiconductor manufacturing across the entire value chain. As an elected member of the Semiconductor Climate Consortium (SCC) Governing Council, Katharina reinforces her commitment to drive positive change within the semiconductor ecosystem. Her dynamic leadership places her at the forefront of digitalization and sustainability solutions – transforming the everyday through innovative technologies.

Previously, Katharina held various strategic positions within Siemens, including heading the Research & Pre-Development department. She championed sustainable practices and contributed to the development of next-generation Siemens products.

She holds a Master of Science degree from the Catholic University Eichstaett-Ingolstadt.

## Topic Coming Soon

B. Frenkel  
Member of the Executive Board Purchase  
Dr. Ing. h.c. F. Porsche AG, Stuttgart, Germany



### Abstract

Coming Soon

### Biography

1963 Born in Hof (Saale), Germany

1982 A-Level Certificate of education (Abitur) in Hof 1982 Studies in chemistry at Bayreuth University and rubber technology at Hannover University

1984 Various posts in development, production, sales and quality assurance, Helsa-Werke, Gefrees

1997 Quality Auditor, Valeo Thermal Systems, Rodach

1999 Manager Supplier Development Europe, TRW Automotive, Alfdorf

2001 Head of Quality Systems and Methods of Dr. Ing. h.c. F. Porsche AG

2006 Head of Central Training of Dr. Ing. h.c. F. Porsche AG

2013 Head of Sales Network Management & Development of Dr. Ing. h.c. F. Porsche AG 2017 Head of Region Europe of Dr. Ing. h.c. F. Porsche AG

2019 Member of the Supervisory Board of Dr. Ing. h.c. F. Porsche AG

2021 Member of the Executive Board Purchases of Dr. Ing. h.c. F. Porsche AG

References

## Accelerating Innovation with Industry-grade Platforms

C. Mazure  
Chief Strategy Officer  
Institute of Microelectronics – A\*STAR, Singapore,  
Singapore



### Abstract

Shortening the time from innovation to industrialization is essential. A\*STAR, Singapore, is accelerating the development of More-than-Moore applications through its R&D Catapult platforms. The platforms enable design-process-packaging co-optimization for early feasibility studies to prototyping for academia, public agencies and companies. We highlight 3 Catapult platforms: advanced packaging, piezo-MEMS and SiC. Advanced packaging: Our advanced packaging platform addresses semiconductor system scaling towards trillions of transistors in a single energy efficient package. We offer advanced fan-out wafer level packaging, 2.5D interposers, chip-to-wafer micro-bump 3D integration, wafer-to-wafer hybrid bonding and chip-to-wafer hybrid bonding to meet the needs of Power-Performance-Formfactor-Cost (PPFC) in semiconductor systems.

Piezo-MEMS: We have established the world's first Piezo-MEMS 'Lab-in-Fab' platform, where R&D and manufacturing are performed in the same fab – the same equipment, talent and recipes. This enables quicker, less costly and derisked development and commercialization of MEMS devices.

SiC: Our 200mm SiC platform is vertically integrated from epitaxy to power module packaging and testing for reliability and performance. We use superjunction trench MOSFETs as our R&D vehicle, making it available for the first time to academic and fabless innovators.

### Biography

Dr. Carlos Mazure has been working close to A\*STAR as an advisor since May 2021. On July 2024 he joined the Institute of Microelectronics – A\*STAR as Chief Strategy Officer.

With 40 years of experience in the global semiconductor industry, Dr. Carlos Mazure is presently member of several international advisory committees and company boards in Singapore and Europe.

Chairman and Executive Director of the SOI Industry Consortium since July 2014 through December 2020.

Under his leadership the SOI Industry Consortium has been promoting with the SOI ecosystem the development of the SOI platforms worldwide and helping accelerate the SOI market growth. The SOI Industry Consortium joined the industry association SEMI in January 2021, where Carlos Mazure was an advisor till December 2021 Carlos Mazure was with Soitec till October 2020. Executive Vice President and Advisor to the CEO since April 2019, and EVP & CTO, Head of Corporate R&D and CTO at Soitec from January 2001 through March 2019.

Prior to Soitec, from 1994 through 2000 Carlos was with Infineon (Munich, Germany), and initiated Infineon/Toshiba FeRAM Alliance in Japan. From 1993 through 1994 he worked for IBM/Infineon DRAM Alliance (Fishkill, NY); and from 1990 through 1993 at Advanced Products Research and Development Laboratory (APRDL), Motorola (Austin, Texas) on BiCMOS ultra fast SRAMs. Carlos started his career at the Siemens Corporate R&D in Munich, Germany, in 1984.

Carlos Mazure is IEEE Fellow, PhD from the Technical University Munich,

References